

PNP Silicon Digital Transistor

- Switching circuit, inverter, interface circuit, driver circuit
- Built in bias resistor ($R_1 = 10 \text{ k}\Omega$, $R_2 = 10 \text{ k}\Omega$)
- BCR183S / U: Two internally isolated transistors with good matching in one multichip package
- BCR183S / U: For orientation in reel see package information below
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101

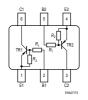




BCR183 BCR183W

BCR183S BCR183U





Туре	Marking Pin Configuration				Package			
BCR183	WMs	1=B	2=E	3=C	-	-	-	SOT23
BCR183S	WMs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SOT363
BCR183U	WMs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SC74
BCR183W	WMs	1=B	2=E	3=C	-	-	-	SOT323



Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{\sf CEO}$	50	V
Collector-base voltage	V_{CBO}	50	
Input forward voltage	V _{i(fwd)}	40	
Input reverse voltage	$V_{i(rev)}$	10	
Collector current	I _C	100	mA
Total power dissipation-	P_{tot}		mW
BCR183, <i>T</i> _S ≤ 102°C		200	
BCR183S, <i>T</i> _S ≤ 115°C		250	
BCR183U, <i>T</i> _S ≤ 118°C		250	
BCR183W, <i>T</i> _S ≤ 124°C		250	
Junction temperature	T_{j}	150	°C
Storage temperature	$T_{\rm stg}$	-65 150	

Thermal Resistance

Parameter	Symbol	Value	Unit			
Junction - soldering point ¹⁾	R _{thJS}		K/W			
BCR183		≤ 240				
BCR183S		≤ 140				
BCR183U		≤ 133				
BCR183W		≤ 105				

 $^{^{1}}$ For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)



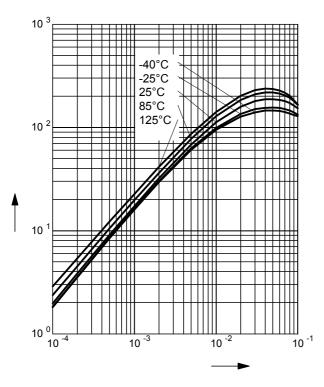
Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified **Symbol Values** Unit **Parameter** min. typ. max. **DC Characteristics** $V_{(BR)CEO}$ ٧ 50 Collector-emitter breakdown voltage $I_{\rm C}$ = 100 μ A, $I_{\rm B}$ = 0 Collector-base breakdown voltage $V_{(BR)CBO}$ 50 $I_{\rm C} = 10 \; \mu {\rm A}, \; I_{\rm E} = 0$ Collector-base cutoff current 100 nΑ I_{CBO} - $V_{\rm CB} = 40 \text{ V}, I_{\rm E} = 0$ 0.75 mΑ Emitter-base cutoff current *I*_{EBO} $V_{\rm EB}$ = 10 V, $I_{\rm C}$ = 0 DC current gain¹⁾ 30 h_{FE} $I_{\rm C}$ = 5 mA, $V_{\rm CE}$ = 5 V Collector-emitter saturation voltage¹⁾ ٧ V_{CEsat} 0.3 $I_{\rm C}$ = 10 mA, $I_{\rm B}$ = 0.5 mA Input off voltage $V_{i(off)}$ 8.0 1.8 $I_{\rm C}$ = 100 μ A, $V_{\rm CE}$ = 5 V $V_{i(on)}$ Input on voltage 1 2.5 $I_{\rm C}$ = 2 mA, $V_{\rm CE}$ = 0.3 V R_1 7 Input resistor 10 13 $\mathsf{k}\Omega$ R_1/R_2 0.9 1 1.1 Resistor ratio **AC Characteristics** f_{T} MHz Transition frequency 200 $I_{\rm C}$ = 10 mA, $V_{\rm CE}$ = 5 V, f = 100 MHz 3 рF Collector-base capacitance C_{cb} $V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$

¹Pulse test: t < 300µs; D < 2%



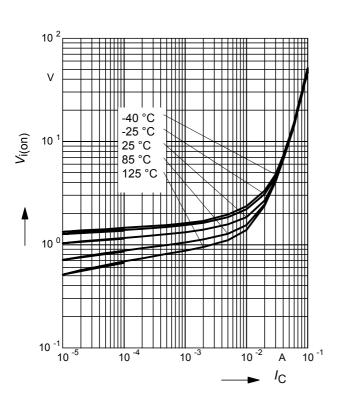
DC current gain $h_{FE} = f(I_C)$

 V_{CE} = 5 V (common emitter configuration)



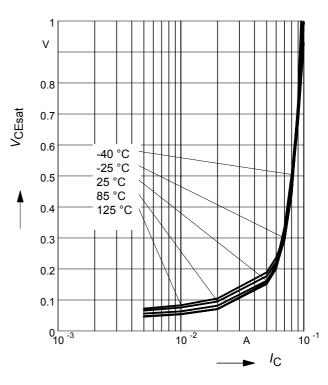
Input on Voltage $V_{I(On)} = f(I_C)$

 V_{CE} = 0.3V (common emitter configuration)



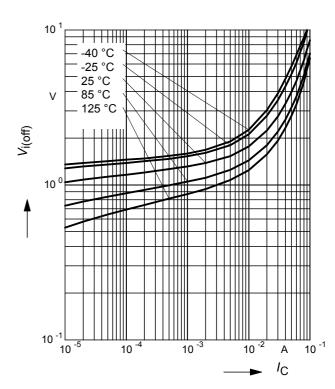
Collector-emitter saturation voltage

 $V_{CEsat} = f(I_{C}), I_{C}/I_{B} = 20$



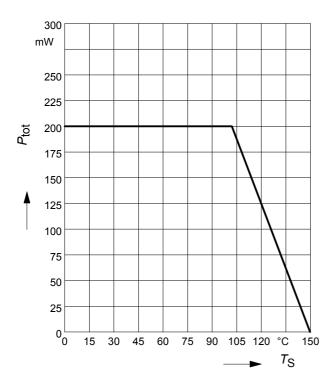
Input off voltage $V_{i(Off)} = f(I_C)$

 V_{CE} = 5V (common emitter configuration)

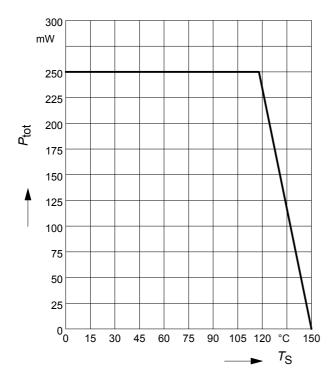




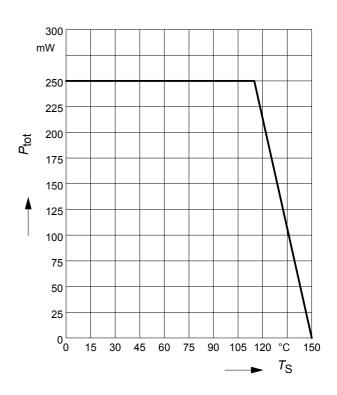
Total power dissipation $P_{tot} = f(T_S)$ BCR183



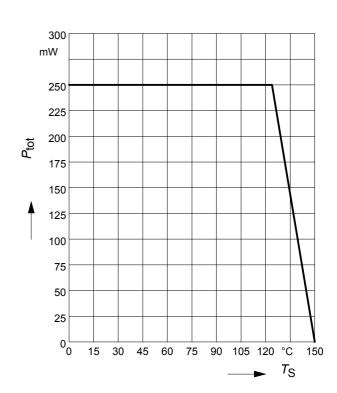
Total power dissipation $P_{tot} = f(T_S)$ BCR183U



Total power dissipation $P_{tot} = f(T_S)$ BCR183S

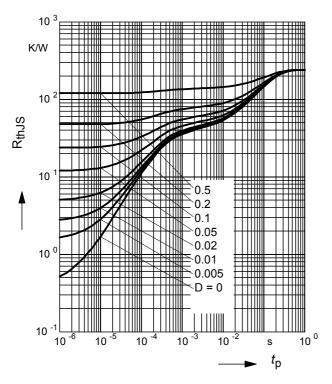


Total power dissipation $P_{tot} = f(T_S)$ BCR183W

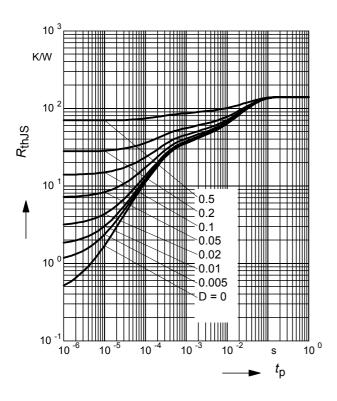




Permissible Pulse Load $R_{thJS} = f(t_p)$ BCR183

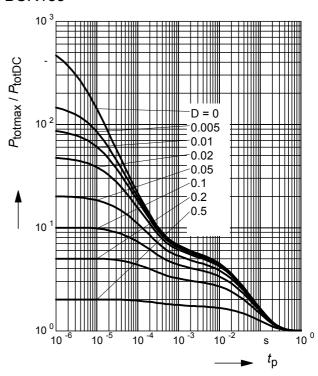


Permissible Puls Load $R_{thJS} = f(t_p)$ BCR183S



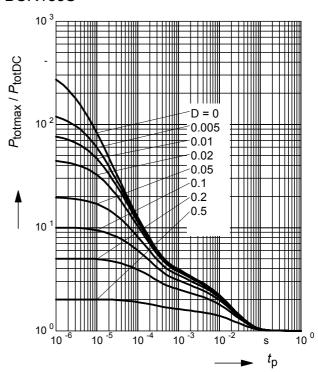
Permissible Pulse Load

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$ BCR183



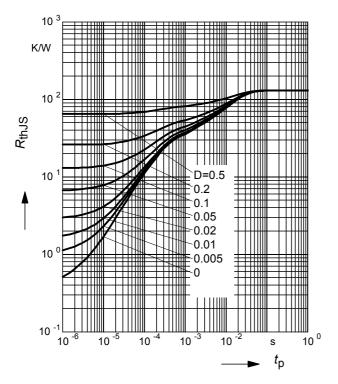
Permissible Pulse Load

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$ BCR183S

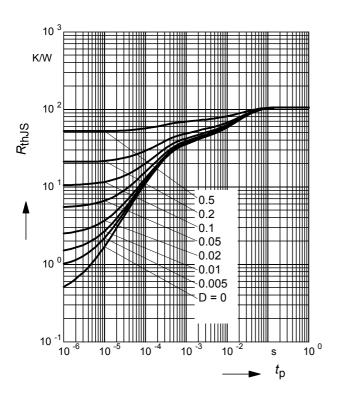




Permissible Puls Load $R_{thJS} = f(t_p)$ BCR183U

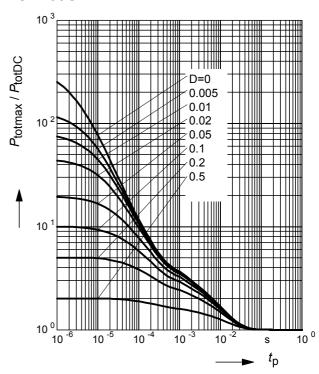


Permissible Puls Load $R_{thJS} = f(t_p)$ BCR183W



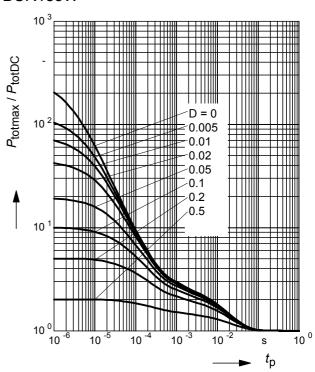
Permissible Pulse Load

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$ BCR183U

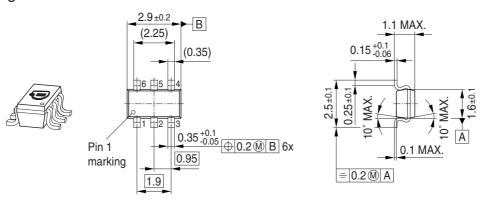


Permissible Pulse Load

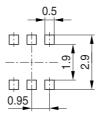
 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$ BCR183W





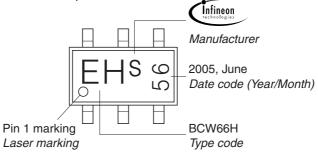


Foot Print



Marking Layout (Example)

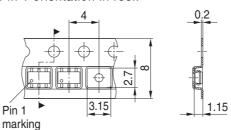
Small variations in positioning of Date code, Type code and Manufacture are possible.



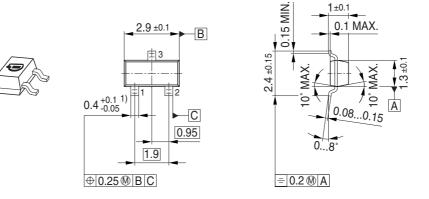
Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

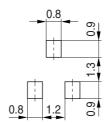
For symmetric types no defined Pin 1 orientation in reel.





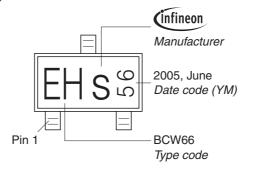


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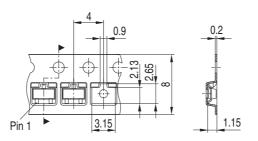
1) Lead width can be 0.6 max. in dambar area

Marking Layout (Example)



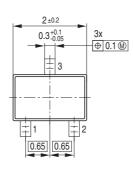
Standard Packing

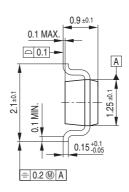
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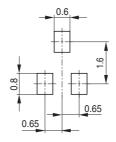




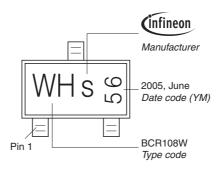




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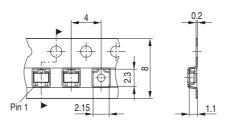


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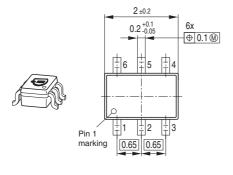


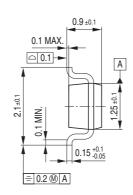
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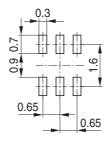






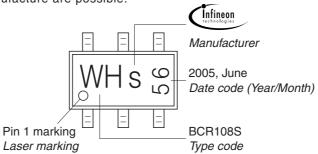


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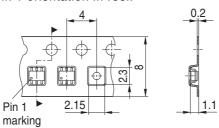
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For symmetric types no defined Pin 1 orientation in reel.





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